

Product Update

Subject:	DiskOnChip technology upgrade to 64Mbits flash shrink die		
Products:	DiskOnChip 2000	Part Number:	MD2200-Dxx, MD2201-Dxx
Update #:	PU0700	Date:	February 29, 2000

Description:

Effective March 1,2000, all DiskOnChip 2000 products which are based on 64Mbits flash devices will be upgraded to a newer shrink flash die. Since more dies can be produced from each wafer, production capacity is increased, allowing improvements in delivery lead-time and better cost structure.

The DiskOnChip products based on the new 64Mbit flash shrink die are compatible with the previous die version both on software and electrical interface. The mechanical form factor of the products is not affected by this change.

This change applies to the following products:

- MD2200-D08 (low profile, 3.3V & 5V)
- MD2200-D16 (low profile, 3.3V & 5V)
- MD2200-D24 (low profile, 3.3V & 5V)
- MD2201-D32 (high profile, 3.3V & 5V)
- MD2201-D40 (high profile, 3.3V & 5V)
- MD2201-D48 (high profile, 3.3V & 5V)
- MD2201-D72 (high profile, 3.3V & 5V)

All other DiskOnChip products are not affected by this change.

Reason of change:

Previous 64Mbit flash devices are not available anymore.

Marking changes:

All DiskOnChip affected will be marked by the prefix character "C" within the revision (e.g. C1.21 instead of 1.21) on the label of the DiskOnChip device.

DiskOnChip Gang programmer support:

The DiskOnChip GANG programmer support is not affected by this change.

Please contact your M-Systems' representative, or refer to M-Systems' web site (www.m-sys.com), for any further information or guidance.

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